Amendments to the Claims:

Claims 1 and 3 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Currently Amended) A method for connecting a horizontally stacked plurality of primary integrated circuit packages on a substrate having a plurality of circuits thereon, each primary integrated circuit package having a plurality of outer leads and having a plurality of sides, using a cage having an open side, comprising:

providing a plurality of primary integrated circuit packages, each primary integrated circuit package having a plurality of peripheral sides, a top, and a bottom and having a plurality of leads extending from one peripheral side ~~opposed sides~~ thereof;

providing a cage including an open top, an open bottom, at least three attached adjacent peripheral sides and portions of a fourth peripheral side attached to each of two of the at least three attached adjacent peripheral sides, one side of the attached adjacent peripheral sides having a plurality of conductive buses thereon, the cage enclosing at least three adjacent peripheral sides of the plurality of sides of each primary integrated circuit package of the stacked plurality of primary integrated circuit packages; and

attaching the cage to the substrate, the cage connecting at least one lead extending from a peripheral side of at least one integrated circuit package ~~two outer opposed leads~~ of the plurality of outer leads of the stacked plurality of primary integrated circuit packages to at least one conductive bus of a plurality of spaced transverse conductive buses.

2. (Previously Presented) The method of claim 1, wherein providing the cage further comprises:

providing a cage enclosing more than the at least two sides of the plurality of sides of each primary integrated circuit package of the stacked plurality of primary integrated circuit packages; and

attaching the cage to the substrate, the cage connecting the at least one outer lead of the plurality of outer leads of the stacked plurality of primary integrated circuit packages to the at least one conductive bus of the plurality of spaced transverse conductive buses.

3. (Currently Amended) A method for connecting a horizontally stacked plurality of primary integrated circuit packages on a substrate having a plurality of circuits thereon, each primary integrated circuit package having a plurality of outer leads on a side thereof of ~~and having~~ a plurality of sides, comprising:

providing a cage including an open top, an open bottom, at least three attached adjacent peripheral sides and portions of a fourth peripheral side attached to each of two of the at least three attached adjacent peripheral sides, one side of the attached adjacent peripheral sides having a plurality of conductive buses thereon, the cage enclosing at least three adjacent sides of the plurality of sides of each primary integrated circuit package of the stacked plurality of primary integrated circuit packages, each primary integrated circuit package having opposed leads extending from opposed sides thereof; and

attaching the cage to the substrate, the cage connecting at least one lead extending from a peripheral side of at least one integrated circuit package ~~two outer opposed leads~~ of the plurality of outer leads of the stacked plurality of primary integrated circuit packages to at least one conductive bus of a plurality of spaced transverse conductive buses.

4. (Withdrawn) A method for connecting a horizontally stacked plurality of primary integrated circuit packages on a substrate having a plurality of circuits thereon, each primary integrated circuit package having a plurality of outer leads and having a plurality of sides, comprising:

providing a cage enclosing at least three sides of the plurality of sides of each primary integrated circuit package of the stacked plurality of primary integrated circuit packages; and

attaching the cage to the substrate using one of adhesive and snap pins fitting in holes in the substrate, the cage connecting at least one outer lead of the plurality of outer leads of the stacked plurality of primary integrated circuit packages to at least one conductive bus of a plurality of spaced transverse conductive buses, with a portion of a semi-continuous flexible tape located within the cage.